



DATE: June 8, 2022

PCN #: 2585 – Special Customer part Specification (SCS) Parts – Future Electronics

PCN Title: Qualified Additional Assembly/Test (A/T) Sites, Wafer Fab Backend IMD Material and Process, and Package Outline Dimension Change

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

**PCN-2585 REV 1 – SCS –
FUTURE ELECTRONICS**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
June 8, 2022	September 8, 2022	Analog Semiconductors	A/T Sites, Wafer Fab Backend IMD Material and POD Change	2585
TITLE				
Qualified Additional Assembly/Test (A/T) Sites, Wafer Fab IMD Backend, and Package Outline Dimension Change				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified the following additional Assembly and Test (A/T) sites for select products: Diodes internal assembly and test site (SAT) located in Shanghai, China, and Shanghai SIMAT Microelectronics Technology (SIMAT) located in Shanghai, China, and Greatek located in Toufen, Taiwan.</p> <p>Diodes has also qualified high-density plasma (HDP) oxide chemical vapor deposition (CVD) as new intermetallic dielectric (IMD) material and process for select products. Some products will also be subject to a change of a respective package outline dimension (POD), in particular package height.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p>				
IMPACT				
Continuity of Supply. There will be no change to the Form, Fit or Function of products affected, unless specifically indicated in Table A below.				
PRODUCTS AFFECTED				
Table 1 - Qualified Addition A/T Site (SAT) Table 2 - Qualified Additional Wafer Fab IMD Backend Material and Process and Additional A/T Site (GTK) Table 3 - Qualified Additional A/T Site (SIMAT) Table 4 – POD Change from 2.5+-0.1mm to 2.4+-0.1mm (See Table A) Table 5 -Qualified Additional A/T Site (GTK) Table 6 - Qualified Additional Wafer Fab Backend IMD Material and Process				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notice/diodes-product-change-notice/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				



FUTURE ELECTRONICS

SCS Parts - Tables 1, 2, 4 – N/A

Table 3 - Qualified Additional A/T Site (SIMAT)

NONE					
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Table 5 - Qualified Additional A/T Site (GTK)

NONE					

Table 6 - Qualified Additional Wafer Fab Backend IMD Material and Process

PI3B3126QEX-2017	PI3B3253LEX-2017	PI3B3257LE-2017	PI3B3257LEX-2017	PI3B3257QEX-2017	